

# STTH108

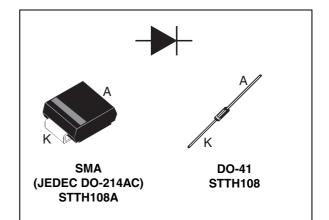
## High voltage ultrafast rectifier

### Features

- Low forward voltage drop
- High reliability
- High surge current capability
- Soft switching for reduced EMI disturbances
- Planar technology

### Description

The STTH108, which is using ST ultrafast high voltage planar technology, is specially suited for free-wheeling, clamping, snubbering, demagnetization in power supplies and other power switching applications.



### Table 1. Device summary

Symbol	Value			
I <sub>F(AV)</sub>	1 A			
V <sub>RRM</sub>	800 V			
T <sub>j</sub> (max)	175 °C			
V <sub>F</sub> (max)	1.25 V			

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## 1 Characteristics

Table 2.	Absolute ratings (limiting values)

Symbol	Parameter			Value	Unit	
V <sub>RRM</sub>	Repetitive peak reverse vol	tage			800	V
V <sub>(RMS)</sub>	Voltage rms				560	V
	Average forward ourrent	SMA	T <sub>L</sub> = 110 °C	$\delta = 0.5$	1	А
IF(AV)	Average forward current	DO-41	T <sub>L</sub> = 130 °C	$\delta = 0.5$	I	А
	Forward Surga ourrant	SMA		SMA	20	А
IFSM	Forward Surge current t = 8.3 ms		DO-41	25	A	
T <sub>stg</sub>	Storage temperature range			-50 to + 175	°C	
Тj	Maximum operating junction temperature				175	°C

### Table 3. Thermal resistance

Symbol		Parameter			
D	Junction to lead		SMA	30	
R <sub>th(j-l)</sub>	Junction to lead	Lead length = 10 mm	DO-41	45	°C/W
R <sub>th(j-a)</sub>	Junction to ambient	Lead length = 10 mm	DO-41	110	

### Table 4. Static electrical characteristics

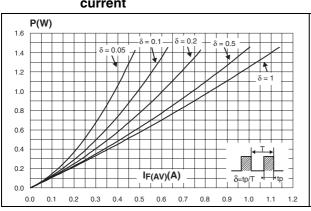
Symbol	Parameter	Tests conditions		Min.	Тур.	Max.	Unit
	Reverse leakage	T <sub>j</sub> = 25 °C	V <sub>B</sub> = 800 V			5	μA
<sup>I</sup> R	current	$T_j = 125 \text{ °C}$ $V_R = 0$	v <sub>R</sub> – 000 v		1	50	μΑ
V <sub>F</sub>	Earward voltage drop	$T_j = 25 \text{ °C}$				1.65	V
۴F	Forward voltage drop	T <sub>j</sub> = 125 °C	I <sub>F</sub> = 1 A		0.89	1.25	V

To evaluate the conduction losses use the following equation: P = 1.05 x  $I_{F(AV)}$  + 0.20  $I_{F}{}^{2}_{(RMS)}$ 

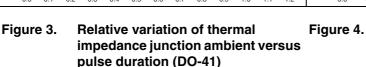
### Table 5. Dynamic electrical characteristics

Symbol	Parameter	Tests conditions		Min.	Тур.	Max.	Unit
t <sub>rr</sub>	Reverse recovery time	T <sub>j</sub> = 25 °C	$I_{F} = 0.5 \text{ A},$ $I_{rr} = 0.25 \text{ A}$ $I_{R} = 1 \text{ A}$			75	ns
t <sub>fr</sub>	Forward recovery time	T <sub>j</sub> = 25 °C	$\label{eq:IF} \begin{array}{l} I_F = 1 \text{ A}, \\ dI_F/dt = 50 \text{ A/ms} \\ V_{FR} = 1.1 \text{ x } V_F \text{max} \end{array}$			200	ns
V <sub>FP</sub>	Forward recovery voltage	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 1 A, dI <sub>F</sub> /dt = 50 A/ms			12	V

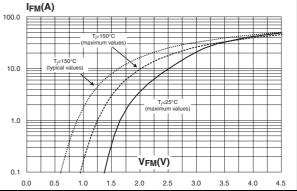




# Figure 1. Conduction losses versus average Figure 2. Forward current forward



. Forward voltage drop versus forward current



Relative variation of thermal impedance junction ambient versus pulse duration (epoxy FR4) (SMA)

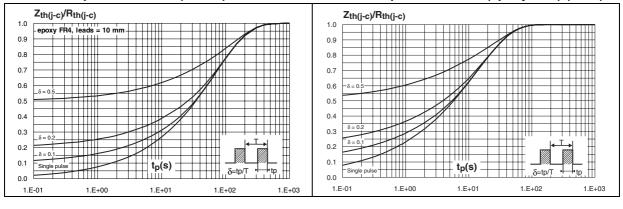
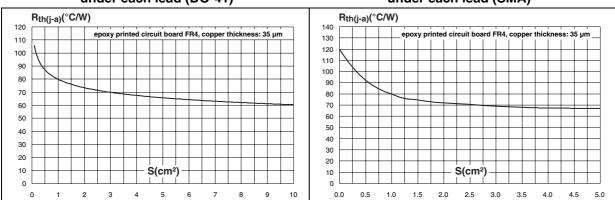


Figure 5. Thermal resistance junction to ambient versus copper surface under each lead (DO-41)

Figure 6. Thermal resistance junction to ambient versus copper surface under each lead (SMA)





## 2 Package information

- Epoxy meets UL 94, V0
- Band indicates cathode
- Bending method (DO-41): see Application note AN1471

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <u>www.st.com</u>. ECOPACK<sup>®</sup> is an ST trademark.

Table 6. SMA dimensions

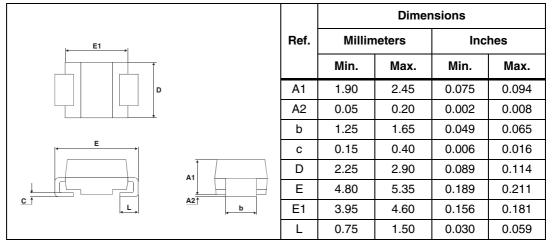
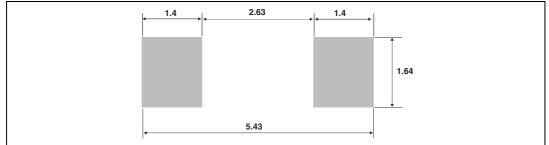


Figure 7. Footprint (dimensions in mm)



### Table 7. DO-41 (plastic) package dimensions

		Dimer	nsions	
 Ref.	Millim	neters	Inc	hes
	Min.	Max.	Min.	Max.
Α	4.07	5.20	0.160	0.205
В	2.04	2.71	0.080	0.107
С	25.4		1	
D	0.71	0.86	0.028	0.034

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# **3** Ordering information

### Table 8. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STTH108	STTH108	DO-41	0.34 g	2000	Ammopack
STTH108A	H08	SMA	0.068 g	5000	Tape and reel
STTH108RL	STTH108	DO-41	0.34 g	5000	Tape and reel

## 4 Revision history

### Table 9. Document revision history

Date	Revision	Changes	
Jan-2003	2	Last update.	
30-Sep-2009	3	Updated table 7 package dimensions.	



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